IGBT Modules

Power Module (V series) 600V / 400A / 2-in-1 package

■ Features

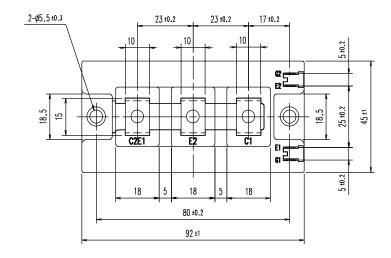
AC-switch
High speed switching
Voltage drive
Low Inductance module structure

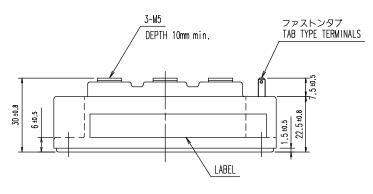
■ Applications

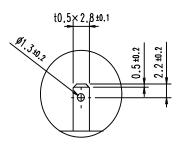
AC-switch for UPS,PCS and etc.

■ Outline drawing (Unit:mm)





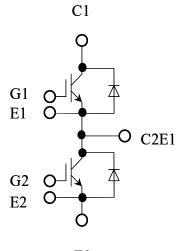




DETAIL TAB TYPE TERMINALS

Weight: 240g (typ.)

■ Equivalent circuit





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■ Absolute maximum ratings (at T_C= 25°C unless otherwise specified)

Items		Symbols	Conditions	Maximum ratings	Units
Collector-Emitter voltage		V _{CES}		600	V
Gate-Emitte	r voltage	V _{GES}		±20	V
Collector current		I _C	Continuous T _C =80	°C 400	A
		I _C pulse	1ms	800	
Collector cu	Hent	-1 _C		400	_ A
		-I _C pulse	1ms	800	
Collector power dissipation		Pc	1 device	1970	W
Junction temperature		T _i		175	
Operating junction temperature		τ		150	
(under switching conditions)		T_{jop}		150	°C
Case temperature		T _c		125	
Storage temperature		T _{stg}		-40 ~ 125	
Isolation	Between terminal and copper base	1/	AC: 1min.	2500	VAC
voltage	(*1)	$V_{\rm iso}$	AC. IIIIII.	2500	VAC
Screw	Mounting	-	M5	2.5 ~ 3.5	N m
torque	Terminals	-	M5	2.5 ~ 3.5	IN III

^(*1) All terminals should be connected together during the test.



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■ Electrical characteristics (at T_j= 25°C unless otherwise specified)

NOTICE:

The external gate resistance ($R_{\rm g}$) shown below is one of our recommend value for the purpose of minimum switching loss. However the optimum $R_{\rm g}$ depends on circuit configuration and/or environment. We recommend that the $R_{\rm g}$ has to be carefully chosen based on consideration if IGBT module matches design criteria, for example, switching loss, EMC/EMI, spike voltage, surge current and no unexpected oscillation and so on.

lto-m-o	Cympholo	Conditions		Characteristics			Units
Items	Symbols			min.	typ.	max.	Units
Zero gate voltage collector current	I _{CES}	V _{GE} =0V,V _{CE} =600V		-	-	2.0	mA
Gate-Emitter leakage current	I _{GES}	V _{CE} =0V,V _{GE} =±20V		-	ı	400	nA
Gate-Emitter threshold voltage	$V_{GE(th)}$	V _{CE} =20V,I _C =400mA		6.2	6.7	7.2	V
	V _{CE(sat)}		T _j =25°C	-	1.90	2.35	
		V_{GE} =15V, I_{C} =400A	T _j =125°C	1	2.20	-	
Collector-Emitter	(terminal)		T _j =150°C	-	2.30	-	V
saturation voltage	V _{CE(sat)} V _{GE}		T _j =25°C	•	1.60	2.05	V
		$V_{\rm GE}$ =15V, $I_{\rm C}$ =400A	T _j =125°C	-	1.90	-	
	(chip)	nip)	T _j =150°C	-	2.00	-	
Internal gate resistance	R _{g(int)}	-		-	2.0	-	Ω
Input capacitance	C ies	V _{CE} =10V, V _{GE} =0V, j	=1MHz		25.6	-	nF
	t on			-	650	-	
Turn-on time	t _r	$V_{\rm CC}$ =300V, $I_{\rm C}$ =400A, $V_{\rm GE}$ =±15V, $R_{\rm g}$ =3.3 Ω , $T_{\rm j}$ =150°C, $L_{\rm s}$ =30nH		-	300	-	nsec
	t _{r(i)}			•	100	-	
Turn-off time	t off			•	600	-	
rum-on ume	t _f			•	70	-	
	V _F		T _i =25°C	-	1.75	2.20	V
Forward on voltage		$V_{GE} = 0 \text{V}, I_{F} = 400 \text{A}$	T _i =125°C	-	1.65	-	
	(terminal)		T _i =150°C	•	1.62	-	
	V _F V _C	V _{GE} =0V,/ _F =400A	T _j =25°C	•	1.60	2.05	
			T _j =125°C	•	1.50	-	
	(chip)		T _j =150°C	•	1.47	-	
Reverse recovery time	t _{rr}	I _F =400A		-	200	-	nsec

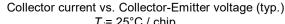
■ Thermal resistance characteristics

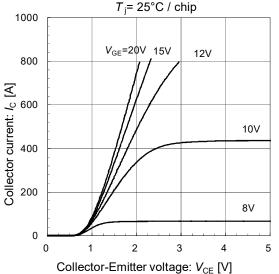
Symbols	Conditions	Characteristics			Units
	Conditions	min.	typ.	max.	UiillS
P	IGBT	-	-	0.076	
th(j-c)	FWD	-	-	0.140	°C/W
R _{th(c-f)}	with thermal compound	-	0.025	-	- C/VV
	R _{th(j-c)}	R _{th(j-c)} IGBT FWD	R _{th(j-c)} IGBT - FWD -	Symbols Conditions min. typ. R th(j-c) IGBT	Symbols Conditions min. typ. max. R _{th(j-c)} IGBT - - 0.076 - - 0.140

^(*1) This is the value which is defined mounting on the additional cooling fin with thermal compound.

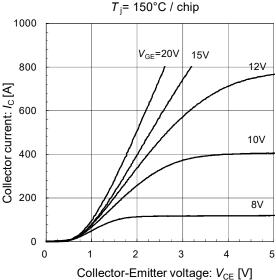


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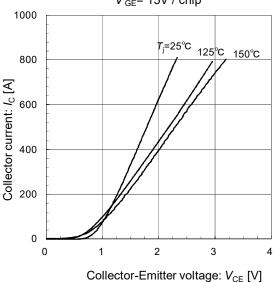




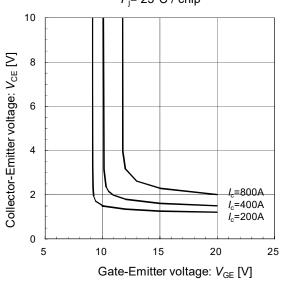
Collector current vs. Collector-Emitter voltage



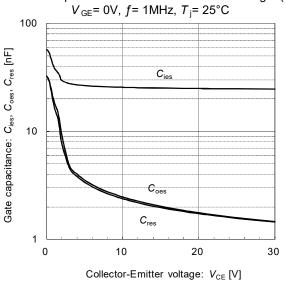
Collector current vs. Collector-Emitter voltage (typ.) V_{GE} = 15V / chip



Collector-Emitter voltage vs. Gate-Emitter voltage (typ.) T_i = 25°C / chip



Gate capacitance vs. Collector-Emitter voltage (typ.)



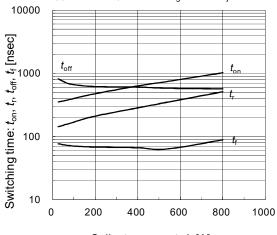
Dynamic gate charge (typ.) $V_{\rm CC}$ =300V, $I_{\rm C}$ =400A, $T_{\rm i}$ =25°C 20 400 15 300 Sollector-Emitter voltage: V_{CE} [V] Gate-Emitter voltage: V_{GE} [V] V_{CE} 200 10 100 5 0 -5 -100 V_{GE} -200 -10 -15 -300 -20 -400 0.0 2.0 3.0 -3.0 -2.0 -1.0 1.0

Gate charge: Q_g [μC]



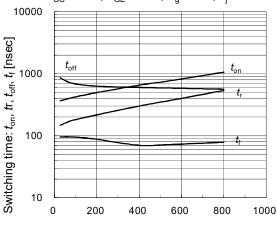
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Switching time vs. Collector current (typ.) V_{CC} =300V, V_{GE} =±15V, R_g =3.3 Ω , T_j =125°C



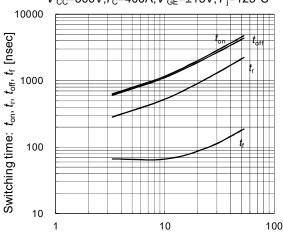
Collector current: Ic [A]

Switching time vs. Collector current (typ.) $V_{CC}=300\text{V}, V_{GE}=\pm15\text{V}, R_g=3.3\Omega, T_j=150^{\circ}\text{C}$



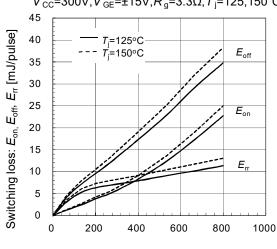
Collector current: I_c [A]

Switching time vs. Gate resistance (typ.) $V_{\text{CC}}=300\text{V}, I_{\text{C}}=400\text{A}, V_{\text{GE}}=\pm15\text{V}, T_{\text{i}}=125^{\circ}\text{C}$



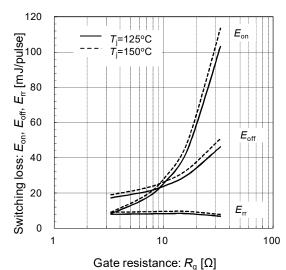
Gate resistance: R_g [Ω]

Switching loss vs. Collector current (typ.) $V_{CC}=300V$, $V_{GE}=\pm15V$, $R_g=3.3\Omega$, $T_i=125$, 150° C

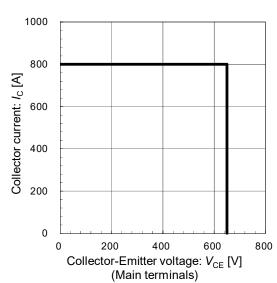


Collector current: I_c [A]

Switching loss vs. Gate resistance (typ.) V_{CC} =300V, I_{C} =400A, V_{GE} =±15V, T_{j} =125,150°C



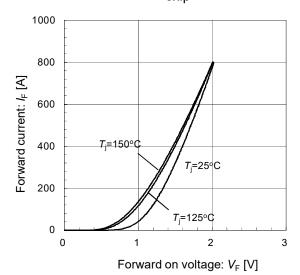
Reverse bias safe operating area (max.) + $V_{\rm GE}$ =15V, - $V_{\rm GE}$ =15V, $R_{\rm g}$ =3.3 Ω , $T_{\rm j}$ =150 $^{\rm o}$ C



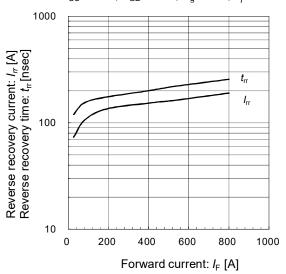


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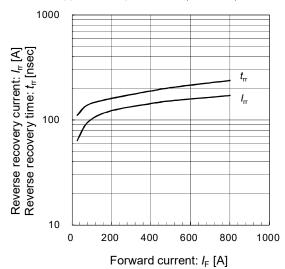
Forward current vs. Forward voltage (typ.) chip



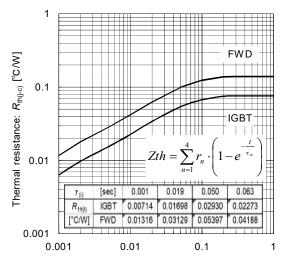
Reverse recovery characteristics (typ.) $V_{CC}=300V$, $V_{GE}=\pm15V$, $R_{o}=3.3\Omega$, $T_{i}=150^{\circ}C$



Reverse recovery characteristics (typ.) V_{CC} =300V, V_{GE} =±15V, R_q =3.3 Ω , T_i =125°C



Transient thermal resistance (max.)



Pulse width : $P_{\rm w}$ [sec]



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